

High Thermal Conductivity Adhesives for Aerospace Applications

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Apple Graphene Materials has launched high thermal conductive adhesive systems which are ideal for space and defense applications. These remarkably versatile nano-adhesives, which are cost-effective and efficient, can be used to attach satellite components and other aerospace equipment. They have very high thermal conductivity and considerable mechanical properties, making them proper candidates in a wide array of industrial sectors.

Following four years of development work [AGM](#) are now offering materials engineers, in the Space and Defence sectors, two unique thermally conductive epoxy paste adhesive systems, AGM TP300 and AGM TP400.

These novel epoxy adhesive systems exhibit high levels of thermal conductivity (between 3 and 6 W/mK), combined with excellent mechanical, adhesive and outgassing performance. Most significantly these properties are achieved with cured resin densities as low as 40% that of competitive conductive adhesives on the market. AGM's TP 300/400 products are therefore highly versatile, while providing end users with significant savings in both mass and cost.

Already being adopted within the industry, AGM's TP 300/400 systems are ideal for use where thermal management is critical in structural bonding or gap filling, across a range of satellite and general space applications.

TP300/400 adhesives are supplied in 2 pack resin and hardener systems. They are supported by an extended performance database, available on short lead-times and supplied in convenient kit sizes to suit customer requirements.

Read the [original article](#) on Applied Graphene Materials.